Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load
For capacitance load, derate current by 20%.

Characteristic	Symbol	B120/B	B130/B	B140/B	B150/B	B160/B	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	20	30	40	50	60	V
RMS Reverse Voltage	$V_{R(RMS)}$	14	21	28	35	42	V
Average Rectified Output Current @ T_T = +130°C	I_O	1.0					A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	30					A

Thermal Characteristics

Characteristic	Symbol	B120/B	B130/B	B140/B	B150/B	B160/B	Unit
Typical Thermal Resistance Junction to Terminal (Note 5)	$R_{\theta JT}$	20					°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150					°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	B120/B, B130/B, B140/B	V_F	-	-	0.5	V	I_F = 1.0A
	B150/B, B160/B		-	-	0.7		I_F = 1.0A
Leakage Current (Note 6)		I_R	-	-	0.5	mA	@ Rated V_R, T_A = +25°C
			-	-	10		@ Rated V_R, T_A = +100°C
Total Capacitance		C_T	-	-	110	pF	V_R = 4V, f = 1MHz

Notes: 5. Thermal Resistance: Junction to terminal, unit mounted on PC board with 5.0 mm^2 (0.013 mm thick) copper pads as heat sink.
6. Short duration pulse test used to minimize self-heating effect.

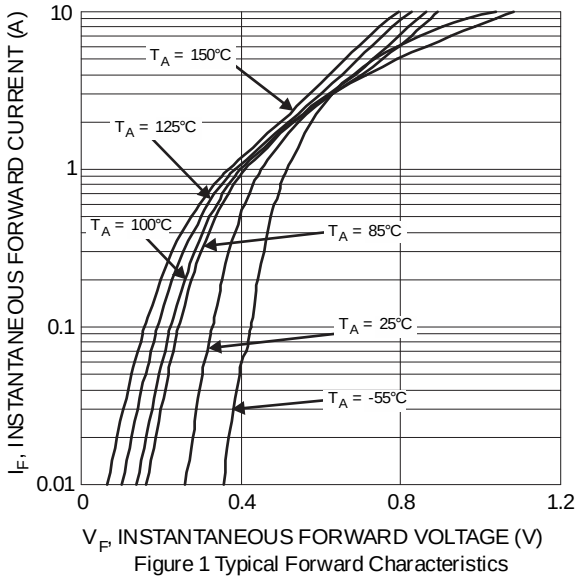


Figure 1 Typical Forward Characteristics

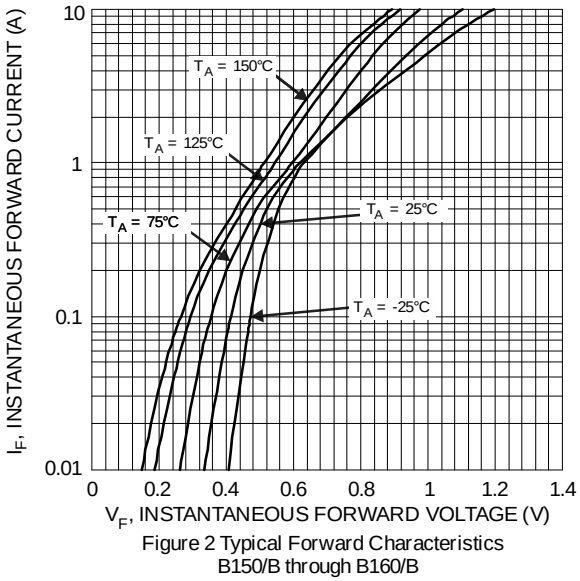


Figure 2 Typical Forward Characteristics
B150/B through B160/B

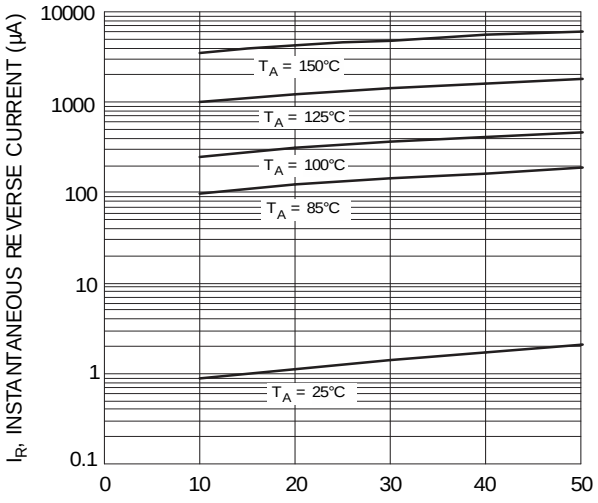


Figure 3 Typical Reverse Characteristics
B120/B through B140/B

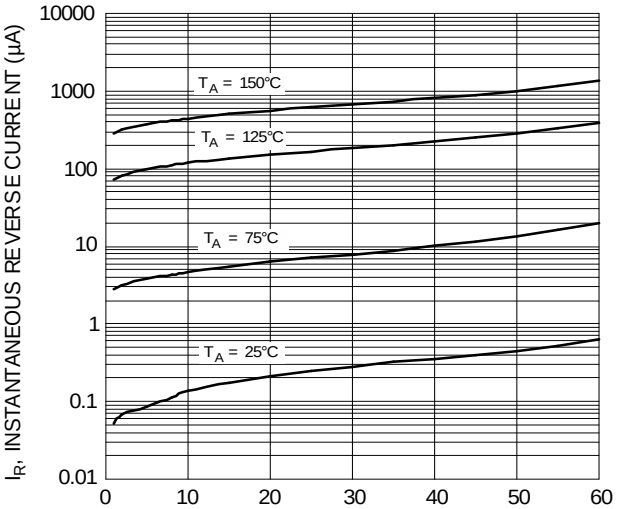


Figure 4 Typical Reverse Characteristics
B150/B through B160/B

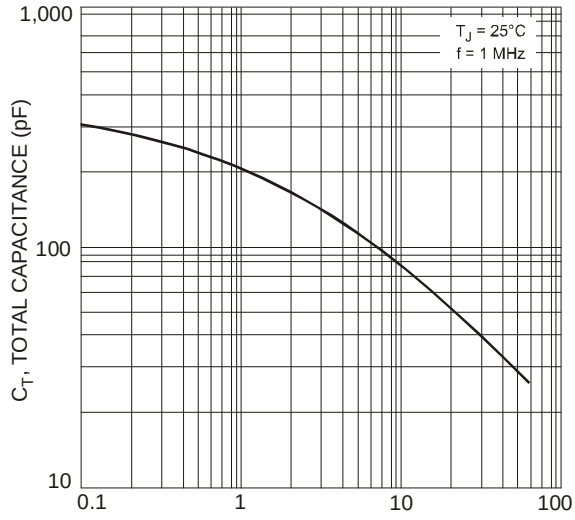


Fig. 5 Total Capacitance vs. Reverse Voltage

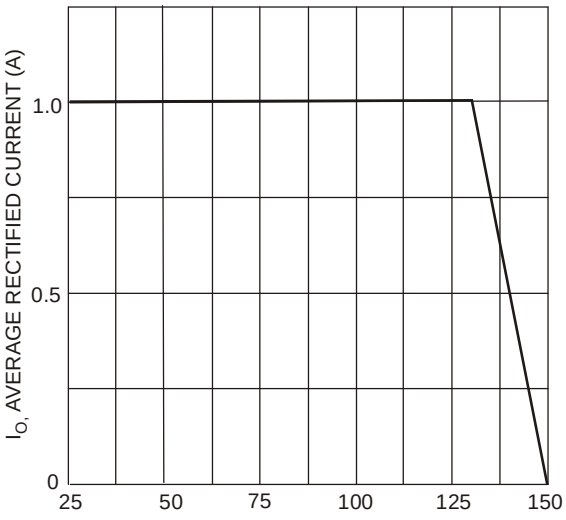


Fig. 6 Forward Current Derating Curve

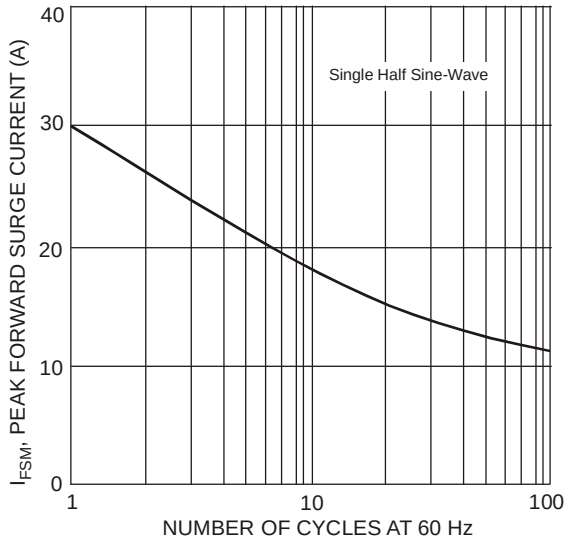
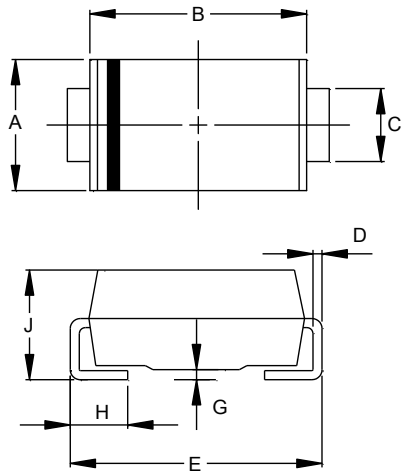


Fig. 7 Max Non-Repetitive Peak Forward Surge Current

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

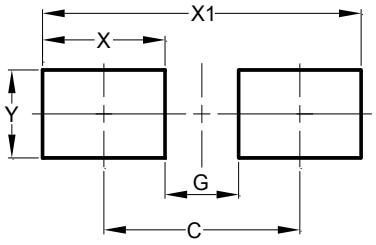


SMA		
Dim	**Min**	**Max**
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.05	0.20
H	0.76	1.52
J	1.96	2.40
All Dimensions in mm		

SMB		
Dim	**Min**	**Max**
A	3.30	3.94
B	4.06	4.57
C	1.96	2.21
D	0.15	0.31
E	5.00	5.59
G	0.05	0.20
H	0.76	1.52
J	2.00	2.50
All Dimensions in mm		

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	SMA (in mm)	SMB (in mm)
C	4.00	4.30
G	1.50	1.80
X	2.50	2.50
X1	6.50	6.80
Y	1.70	2.30

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